

S/N 10/723,474

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Suan J. Boon	Examiner:	DiLinh Nguyen
Serial No.:	10/723,474	Group Art Unit:	2814
Filed:	November 26, 2003	Docket No.:	303.601US2
Title:	ELECTRONIC APPARATUS HAVING AN ADHESIVE LAYER FROM WAFER LEVEL PACKAGING		

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

This responds to the Office Action mailed on December 13, 2007. Please amend the above-identified patent application as follows.

This response is accompanied by a Petition, as well as the appropriate fee, to obtain a one-month extension of the period for responding to the Office Action, thereby moving the deadline for response from March 13, 2008 to April 13, 2008 (Sunday).